What is claimed is:

1   *Sub A 2* 1. A laminate support used in the process of wire

2   bonding a circuit device, comprising a closed woven mesh

3   having strands whose separation distance is equal to or less

4   than the diameter of said wire of said circuit device.

1   2.   The laminate support used in the process of wire

2   bonding a circuit device in accordance with claim 1, wherein

3   said separation distance is no greater than 0.7 mils.

1   3.   The laminate support used in the process of wire

2   bonding a circuit device in accordance with claim 1, wherein

3   said separation distance is between 0.2 and 0.7 mils.

1   *Sub A 3* 4. The laminate support used in the process of wire

2   bonding a circuit device in accordance with claim 1, wherein

3   said laminate support comprises fiberglass.

1   *Sub A3* 5. The laminate support used in the process of wire

2   bonding a circuit device in accordance with claim 1, wherein

3   said laminate support is between approximately 2.5 and 4

4   mils thick.

1   6. The laminate support used in the process of wire

2   bonding a circuit device in accordance with claim 1, wherein

3   said circuit device is a pad of large scale integrated

4   design.

1   7. A laminate support used in the process of wire

2   bonding a circuit device, comprising a closed woven mesh

3   having warp and weave strands, whose separation distance is

4   equal to or less than the thickness of said wire of said

5   circuit device, as measured lengthwise through said closed

6   woven mesh.

1   8. The laminate support used in the process of wire

2   bonding a circuit device in accordance with claim 7, wherein

3   said separation distance is equal to or less than 0.7 mils.

1   9. The laminate support used in the process of wire

2   bonding a circuit device in accordance with claim 7, wherein

3   said separation distance is between 0.2 and 0.7 mils.

1   10. The laminate support used in the process of wire

2   bonding a circuit device in accordance with claim 7, wherein

3   said laminate support comprises fiberglass.

1   11. The laminate support used in the process of wire
2   bonding a circuit device in accordance with claim 7, wherein
3   said laminate support is between approximately 2.5 and 4
4   mils thick.

1   12. The laminate support used in the process of wire
2   bonding a circuit device in accordance with claim 7, wherein
3   said circuit device comprises a pad of large scale
4   integrated design.

1   13. A laminate support used in the process of wire
2   bonding a circuit device, comprising a closed woven mesh
3   having warp and weave strands, whose separation distance is
4   no greater than the diameter of said wire of said circuit
5   device as measured lengthwise through said closed woven
6   mesh, and wherein said separation distance is approximately
7   equal to or less than 0.7 mils.

1   14. The laminate support used in the process of wire
2   bonding a circuit device in accordance with claim 13,
3   wherein said separation distance is between 0.2 and 0.7
4   mils.

1　　　15.　The laminate support used in the process of wire

2　bonding a circuit device in accordance with claim 13,

3　wherein said laminate support comprises fiberglass.

1　　　16.　The laminate support used in the process of wire

2　bonding a circuit device in accordance with claim 13,

3　wherein said laminate support is between approximately 2.5

4　and 4 mils thick.

1　　　17.　The laminate support used in the process of wire

2　bonding a circuit device in accordance with claim 13,

3　wherein said circuit device comprises a pad of large scale

4　integrated design.

1　　　18.　A method for supporting a circuit device during

2　wire bonding, comprising the steps of:

3　　　a)　applying a capillary tool to wire that is to

4　be bonded to a circuit device; and

5　　　b)　supporting said circuit device upon a closed

6　woven mesh whose separation distance between woven strands

7　is less than or equal to a diameter of said wire.

1   19.   The method of claim 18, wherein said separation

2   distance is approximately equal to or less than 0.7 mils.

1   20.   The method of claim 18, wherein said separation

2   distance is between approximately 0.2 and 0.7 mils.